

October, 2013

To: Customers

Change Notice on Package Products

First of all, we would like to take this opportunity to thank you for the excellent business relationship between the two companies and we look forward to a successful ongoing partnership in future.

With this letter, we would like to inform an engineering change of some small type QFP (Quad Flat Package) products which are assembled at one of our subcontractors.

1. Description of Change

- Lead-frame, Mold compound material, Chip thickness
Please refer to attached sheets for detail.

2. Reason of Change

- Because of discontinuation of the relevant lead-frames, our subcontractor needs to change the lead-frame supplier. In this opportunity, they proposed to apply standard conditions to those package products in addition.
- We verified that their plan could achieve same quality level as for current parts.

3. Objective Products

Epson P/N: S*****

Applicable packages are the following:

P-LQFP048-0707-0.50 (QFP12-48Pin)
P-TQFP048-0707-0.50 (TQFP12-48Pin)
P-LQFP100-1414-0.50 (QFP15-100Pin)
P-TQFP100-1414-0.50 (TQFP15-100Pin)
P-LQFP128-1414-0.40 (QFP15-128Pin)

*() Epson Package name

4. Implementation Schedule

- Start EC parts shipment in May 2014
- Depending on your order quantity and our inventory status, the concrete schedule will be determined. It will be available at your sales contact.

5. Requests

In order to secure current lead-frame, please inform us your ordering plan through Apr.2014 **by 24th Oct.2013.**

If you have any questions or concerns, please also let us know **by 24th Oct.2013.**

Your understanding and cooperation will be highly appreciated.

Sincerely yours,

Tomomasa Sakashita
General Manager of IC sales department
Micro Devices Operations Division
SEIKO EPSON CORP.